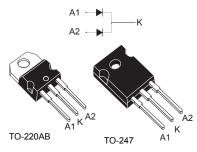


170 V power Schottky rectifier





Features

- High junction temperature capability
- Low leakage current
- · High voltage capabilities
- Good trade-off between leakage current and forward voltage drop
- · Low thermal resistance
- · High frequency operation
- Avalanche specification
- ECOPACK®2 compliant for TO-220AB and TO-247, on demand for D2PAK

Applications

- · Switching diode
- SMPS
- DC/DC converter
- · Telecom power

Description

This dual center tab Schottky rectifier is suited for high frequency switched mode power supplies.

Packaged in TO-247, D²PAK and TO-247, the STPS40170C is optimized for use to enhance the reliability in applications.

Product status link				
STPS40170C				
Product summary				
Symbol Value				
I _{F(AV)}	2 x 20 A			
V_{RRM}	170 V			
T _j	175 °C			
V_F (typ.) 0.69 V				



1 Characteristics

Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified, per diode)

Symbol	Parameter		Value	Unit	
V_{RRM}	Repetitive peak reverse voltage			170	V
I _{F(RMS)}	Forward rms current			60	Α
	A	T _c = 150 °C	Per diode	20	
I _{F(AV)}	F(AV) Average forward current, $\delta = 0.5$ square wave	T _c = 145 °C	Per device	40	Α
I _{FSM}	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal}$			250	Α
P _{ARM}	Repetitive peak avalanche power $t_p = 10 \mu s$, $T_j = 125 °C$			1015	W
T _{stg}	Storage temperature range			-65 to +175	°C
Tj	Maximum operating junction temperature range ⁽¹⁾			175	°C

^{1.} $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 2. Thermal resistance parameters

Symbol	Parameter		Max. value	Unit
D.,	Junction to case	Per diode	1.20	
R _{th(j-c)}	Junction to case	Total	0.85	°C/W
R _{th(c)}	Coupling		0.50	

When the diodes 1 and 2 are used simultaneously:

 ΔT_j (diode 1) = P(diode1) x R_{th(j-c)}(per diode) + P(diode 2) x R_{th(c)}

Table 3. Static electrical characteristics (per diode)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I_ (1)	I _R ⁽¹⁾ Reverse leakage current	T _j = 25 °C	$V_R = V_{RRM}$	-		30	μA
IR ^(*)		T _j = 125 °C		-	7	30	mA
	$V_{F}^{(2)} \qquad \text{Forward voltage drop} \qquad \begin{aligned} & T_{j} = 25 ^{\circ}\text{C} \\ & T_{j} = 125 ^{\circ}\text{C} \\ & T_{j} = 25 ^{\circ}\text{C} \\ & T_{j} = 25 ^{\circ}\text{C} \\ & T_{j} = 125 ^{\circ}\text{C} \end{aligned} \qquad I_{F} = 40 \text{A}$	I_ = 20 A	-		0.92		
V (2)		T _j = 125 °C	IF - 20 A	-	0.69	0.75	
VF(=)		T _j = 25 °C	L = 40 A	-		1.00	V
		T _j = 125 °C	1F - 40 A	-	0.79	0.86	

- 1. Pulse test: $t_p = 5$ ms, $\delta < 2\%$
- 2. Pulse test: t_p = 380 μ s, δ < 2%

To evaluate the conduction losses, use the following equation:

 $P = 0.64 \times I_{F(AV)} + 0.0055 \times I_{F}^{2}_{(RMS)}$

For more information, please refer to the following application notes related to the power losses:

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

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1.1 **Characteristics (curves)**

Figure 1. Average forward power dissipation versus average forward current (per diode)

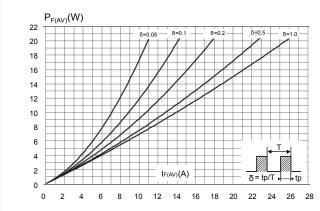


Figure 2. Average forward current versus ambient temperature (δ = 0.5, per diode)

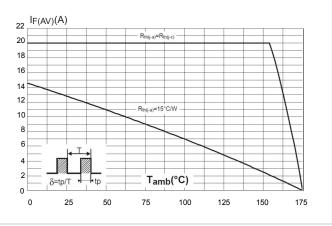


Figure 3. Normalized avalanche power derating versus pulse duration (T_i = 125 °C)

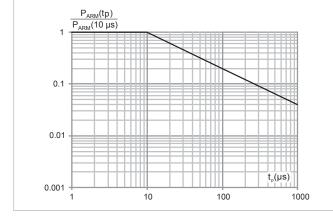
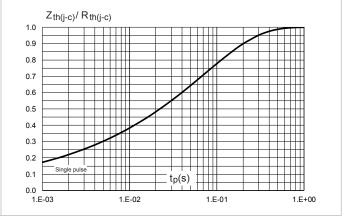


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration



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Figure 5. Reverse leakage current versus reverse voltage applied (typical values, per diode)

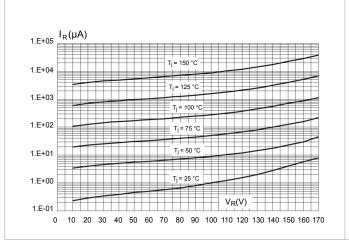


Figure 6. Junction capacitance versus reverse voltage applied (typical values, per diode)

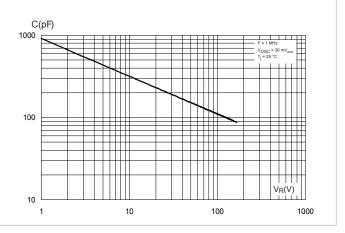


Figure 7. Forward voltage drop versus forward current (per diode)

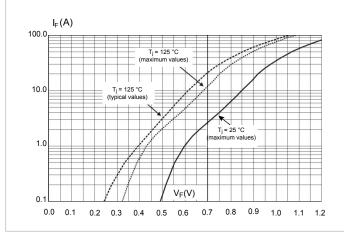
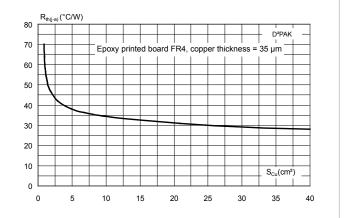


Figure 8. Thermal resistance junction to ambient versus copper surface under tab



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2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

2.1 D²PAK package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)

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E1 c2-THERMAL PAD -*b2* A1 0.25 GAUGE PLANE

Figure 9. D²PAK package outline

Note: This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

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Table 4. D²PAK package mechanical data

	Dimensions				
Ref.	Millim	neters	Inch	ies	
	Min.	Max.	Min.	Max.	
А	4.36	4.60	0.172	0.181	
A1	0.00	0.25	0.000	0.010	
b	0.70	0.93	0.028	0.037	
b2	1.14	1.70	0.045	0.067	
С	0.38	0.69	0.015	0.027	
c2	1.19	1.36	0.047	0.053	
D	8.60	9.35	0.339	0.368	
D1	6.90	8.00	0.272	0.311	
D2	1.10	1.50	0.043	0.060	
Е	10.00	10.55	0.394	0.415	
E1	8.10	8.90	0.319	0.346	
E2	6.85	7.25	0.266	0.282	
е	2.54	typ.	0.100		
e1	4.88	5.28	0.190	0.205	
Н	15.00	15.85	0.591	0.624	
J1	2.49	2.90	0.097	0.112	
L	1.90	2.79	0.075	0.110	
L1	1.27	1.65	0.049	0.065	
L2	1.30	1.78	0.050	0.070	
R	0.4	typ.	0.0	15	
V2	0°	8°	0°	8°	



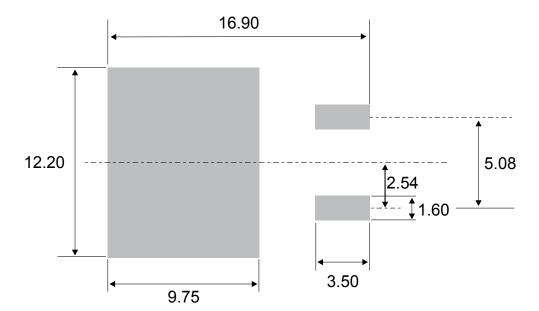


Figure 10. D²PAK recommended footprint (dimensions in mm)

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2.2 TO-247 package information

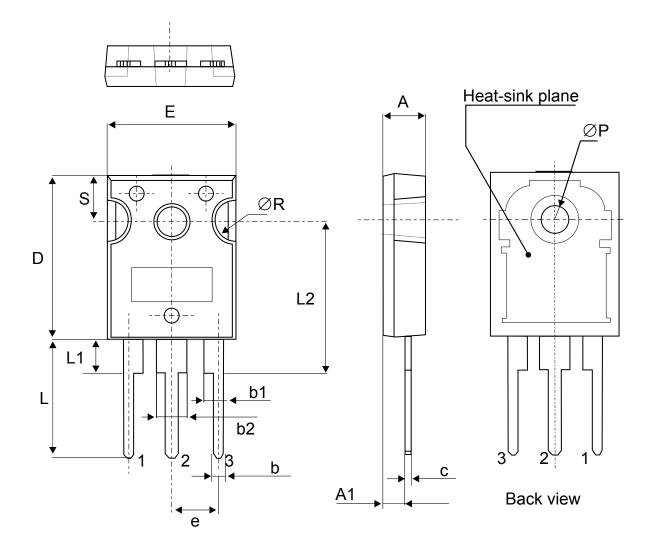
• Epoxy meets UL94, V0

• Cooling method: by conduction (C)

• Recommended torque value: 0.8 N·m

Maximum torque value: 1.0 N·m

Figure 11. TO-247 package outline



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Table 5. TO-247 package mechanical data

			Dimer	nsions		
Ref.		Millimeters			Inches	
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	4.85		5.15	0.191		0.203
A1	2.20		2.60	0.086		0.102
b	1.00		1.40	0.039		0.055
b1	2.00		2.40	0.078		0.094
b2	3.00		3.40	0.118		0.133
С	0.40		0.80	0.015		0.031
D	19.85		20.15	0.781		0.793
E	15.45		15.75	0.608		0.620
е	5.30	5.45	5.60	0.209	0.215	0.220
L	14.20		14.80	0.559		0.582
L1	3.70		4.30	0.145		0.169
L2		18.50			0.728	
ØP	3.55		3.65	0.139		0.143
ØR	4.50		5.50	0.177		0.217
S	5.30	5.50	5.70	0.209	0.216	0.224

^{1.} Inches dimensions given for reference only

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2.3 TO-220AB package information

Epoxy meets UL 94,V0

Cooling method: by conduction (C)
Recommended torque value: 0.55 N·m

• Maximum torque value: 0.70 N·m

Figure 12. TO-220AB package outline

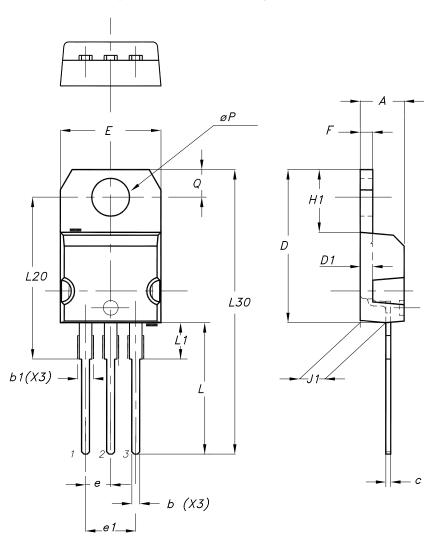


Table 6. TO-220AB package mechanical data

	Dimensions					
Ref.	Millimeters		Ref. Millimeters		Incl	nes
	Min.	Max.	Min.	Max.		
А	4.40	4.60	0.173	0.181		
b	0.61	0.88	0.240	0.035		
b1	1.14	1.55	0.045	0.061		

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	Dimensions				
Ref.	Millim	neters	Inc	hes	
	Min.	Max.	Min.	Max.	
С	0.48	0.70	0.019	0.028	
D	15.25	15.75	0.600	0.620	
D1	1.27	typ.	0.050	typ.	
E	10.00	10.40	0.394	0.409	
е	2.40	2.70	0.094	0.106	
e1	4.95	5.15	0.195	0.203	
F	1.23	1.32	0.048	0.052	
H1	6.20	6.60	0.244	0.260	
J1	2.40	2.72	0.094	0.107	
L	13.00	14.00	0.512	0.551	
L1	3.50	3.93	0.138	0.155	
L20	16.40 typ.		0.646	6 typ.	
L30	28.90 typ.		1.138	3 typ.	
θР	3.75	3.85	0.148	0.152	
Q	2.65	2.95	0.104	0.116	



3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS40170CT	STPS40170CT	TO-220AB	1.95 g	50	Tube
STPS40170CG-TR	STPS40170CG	D ² PAK	1.38 g	10000	Tape and reel
STPS40170CW	STPS40170CW	TO-247	4.36 g	30	Tube

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Revision history

Table 8. Document revision history

Date	Version	Changes
16-Sep-2005	1	Initial release.
01-Jun-2018	2	Updated P _{ARM} value and removed "Normalized avalanche power derating" curves.

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